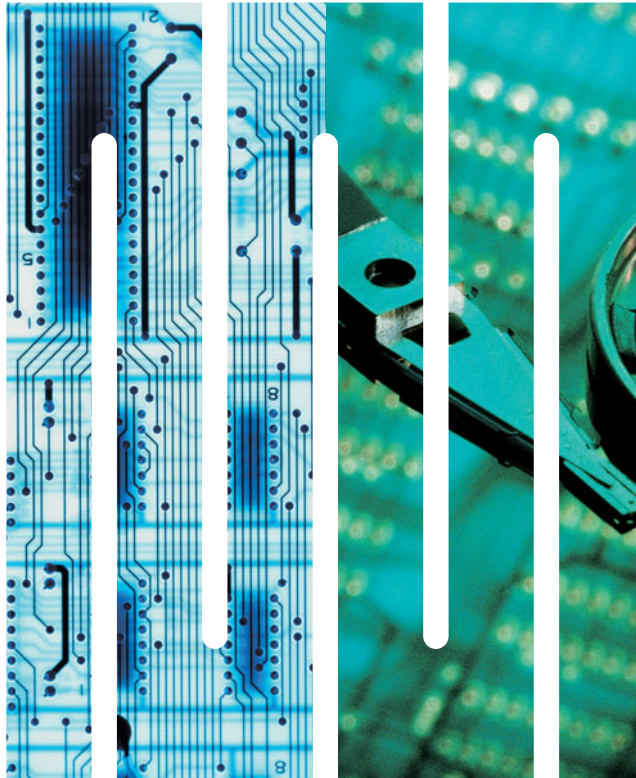


TOYO TANSO CARBON PRODUCTS

# Special Graphite and Compound Material Products



**TOYO TANSO**

Inspiration for Innovation



## **People and carbon An everlasting relationship.**

Carbon has been a part of our life since ancient times. The benefits of carbon have never been far away from humans, making our lives more plentiful and comfortable. In 1974, we were the first company in Japan to successfully develop isotropic graphite, and thereafter rapidly expanding its possibilities. Isotropic graphite became a crucial material of state-of-the-art technologies in industries such as semi-conductors and aerospace. Currently, this material is being used in a wide range of applications over an ever-increasing number of fields. Toyo Tanso is dedicated to unlocking the unlimited potential of carbon and aims to ensure that the beneficial relationship between people and carbon is one that lasts forever.

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- 05. Manufacturing Process
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- 18. Catalog Disclaimers



①



②

# Features of Special Graphite Products

The demand from industry over the years has been for carbon with ever more finer and stable properties. In this context, Toyo Tanso was the pioneer in our industry in developing "isotropic graphite." This is a graphite material with an isotropic structure and properties, created through the cold isostatic press of micro particles. Our isotropic graphite products are used across a wide field of industries. These include: the semi-conductor industry, where innovation is rapidly advancing; the environmentally friendly renewable energy industry; the mold industry, where accuracy is such a priority; and the atomic power industry, where high reliability is essential. Our excellence is recognized by our customers, with whom we grow together. The synergistic effect between our exclusive high purity technology and various coating technologies will ensure that in the future too, we use our position as a leading company to continue to unlock the unlimited potential of carbon.

## ■ Isotropic Graphite

Conventional graphite was anisotropic, which limited its use in many applications. However, isotropic graphite in the same cross section direction has no difference in its properties, making a material that is easy to design and use.

## ■ High Reliability

Isotropic graphite is stronger than conventional graphite due to its micro particle structure. This produces a highly reliable material with a small characteristic variation.

## ■ Ultra Heat Resistance

In an inert atmosphere, stable use is possible even in extremely high temperatures of 2,000°C or more. The material has low thermal expansion and a high coefficient of thermal conductivity, giving it excellent thermal shock resistance and heat distribution properties, with low thermal deformation. It also has a special characteristic whereby its strength increases as the atmospheric temperature gets higher up until 2500°C .

## ■ Excellent Electrical Conductivity

The high and excellent heat resistance mean graphite is the optimum material for applications such as high temperature heaters.

## ■ Excellent Chemical Resistance

With the exception of some strong oxidizers, it is chemically stable. Carbon can be used stably even in environments that cause some metals to corrode.

## ■ Lightweight and Easy to Machine

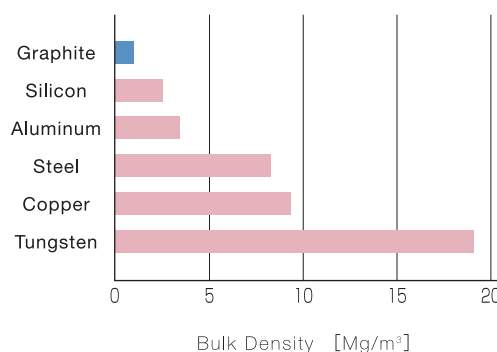
The bulk density is low as compared with metallic materials-enabling a lightweight design. In addition, it has excellent mechanical machining properties-facilitating accurate shaping processes.

## ■ Isotropic Graphite and Anisotropic Graphite

Isotropic High Density Graphite 

Anisotropic Graphite 

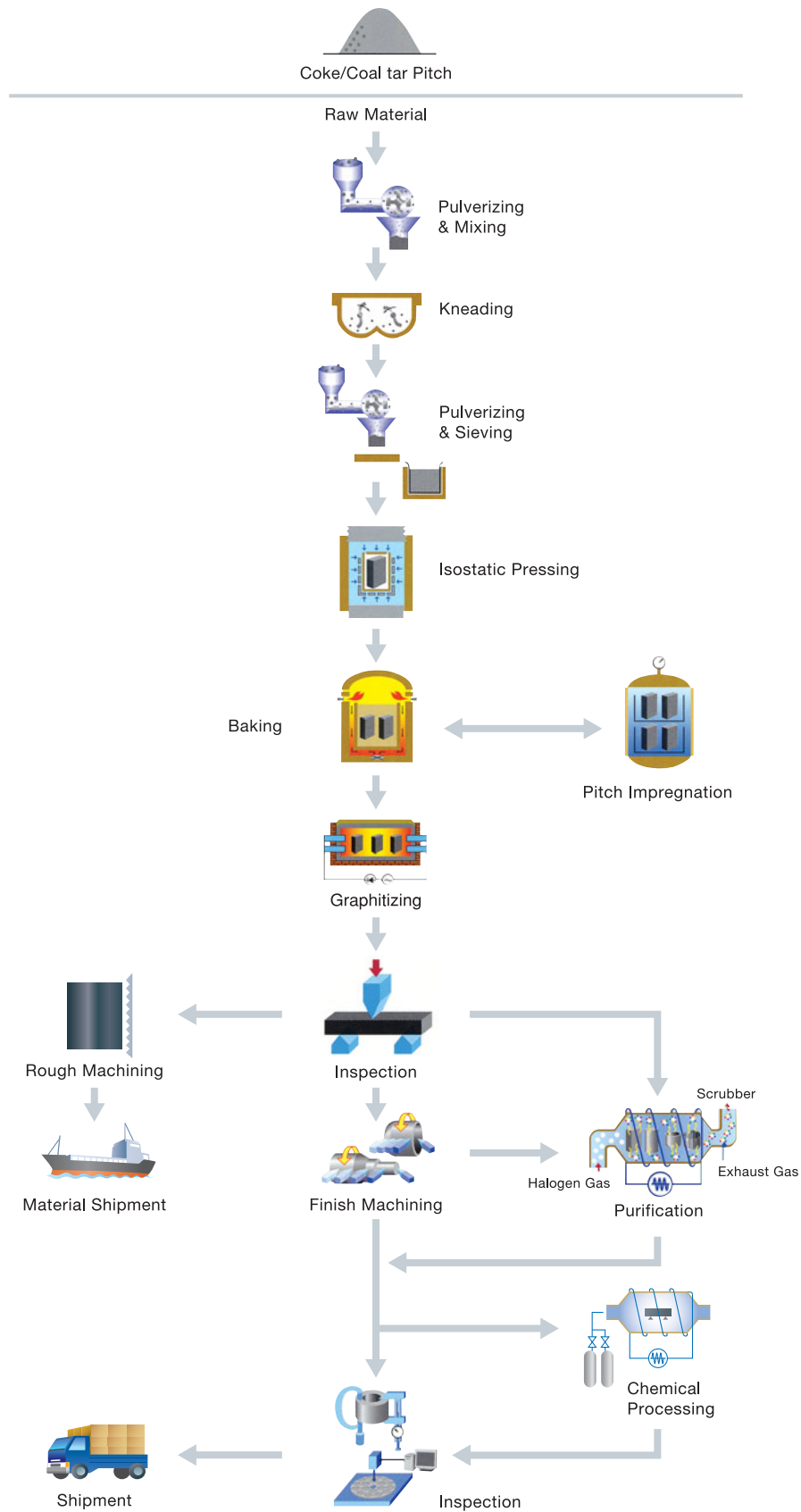
Isotropic high density graphite is different from conventional graphite in that it is isotropic and has a micro particle structure, creating a very strong and highly reliable material with a small variation. This isotropic graphite material resolves the problems associated with conventional anisotropic graphite.



① Single crystal silicon manufacturing equipment

② Critical plasma testing equipment (JT-60) ※Photographs provided by the Japan Atomic Energy Research Institute

# Manufacturing Process



# Application

Toyo Tanso's special graphite products are highly regarded for their excellent performance and reliability and are used across a wide range of fields that are essential in our everyday lives. In the environmental and energy industry, our products are used for solar cell manufacturing, atomic power and aerospace applications. In the electronics industry, we provide materials for polycrystalline silicon and single crystal silicon manufacturing, components in ion implantation equipment, and high-frequency device manufacturing. Basic applications of our products include industrial furnaces, continuous casting dies such as those for copper alloys, optical fibers, and EDM electrodes for mold manufacture. We are also active in supplying products to industries with strong future potential, such as those involved in liquid crystal and white LEDs.

## Environment and Energy

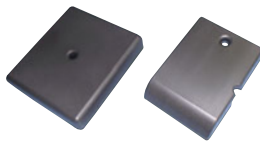
- Solar Cell and Wafer Manufactureing
- Atomic Power : High Temperature Gas Cooled Reactor, Nuclear Fusion
- Fluorine Electrolysis
- Nuclear Fusion
- Fuel Cells
- Aerospace



Side heater



PECVD plate



Nuclear Fusion Reactor  
Plasma First Wall  
※Photo courtesy of Japan Atomic Energy Agency



Rectangular Crucibles



## Electronics

- Silicon Semi-conductor Manufacturing Applications

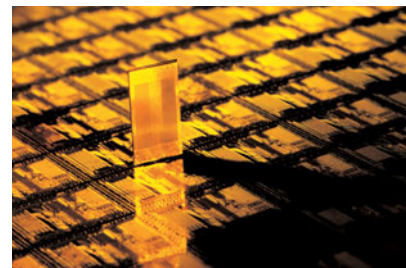
Polycrystalline silicon manufacture  
Single crystal silicon manufacturing equipment  
Susceptors for epitaxial growth  
Plasma CVD electrodes  
Ion implantation  
Glass sealing jigs



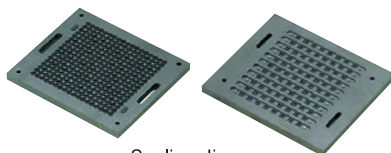
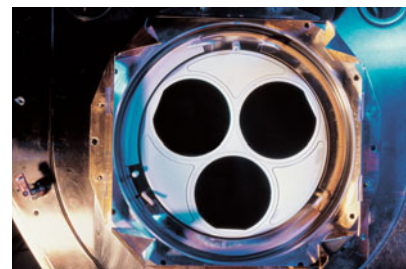
FW type Crucible  
(filament winding)



Crucible



Heater



Sealing Jigs

**Electronics**

● Compound Semi-conductor Manufacturing Applications

Crystal Manufacturing Equipment Parts  
MOCVD Susceptors



MOCVD susceptor

● LCD Panel Manufacturing Applications

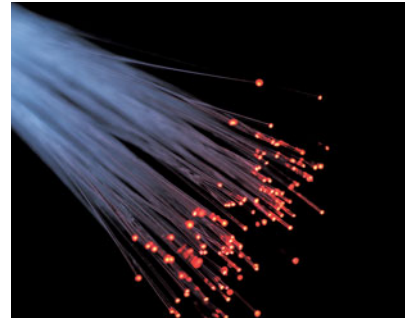
Heater Panels  
Electrode for plasma Etching



Pancake susceptor

● Hard Disk Manufacturing Applications

Sputtering Targets



**Metallurgical**

● Continuous Casting

Dies  
Mandrels



Hot Press Mold (Cut Model)

● Hot Press

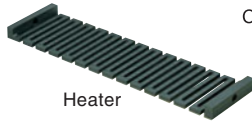
Dies  
Sleeves  
Spacers



Continuous Casting Dies

● Industrial Furnace

Heaters  
Trays



Heater



● Vacuum Evaporation Crucibles

● Gas Analysis Crucibles

● Optical Fiber Manufacturing Applications

Heaters  
Muffle Tube



Vacuum Evaporation Crucibles

● EDM Electrodes



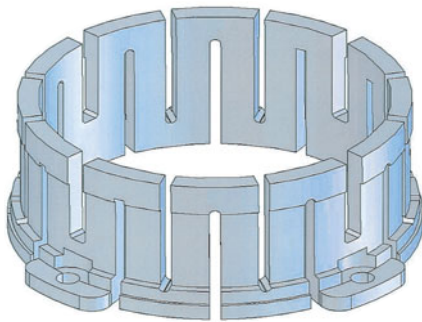
EDM Electrodes



# Toyo Tanso Analysis Technology

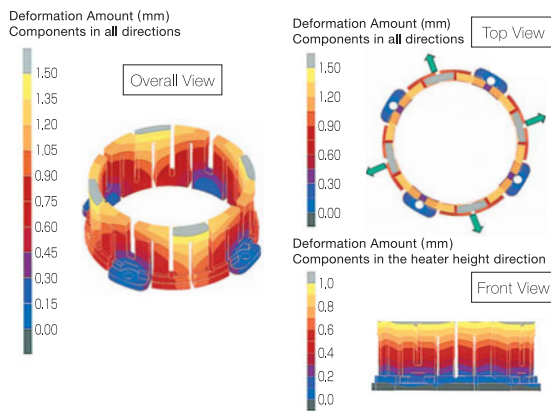
Toyo Tanso uses the high-precision analysis equipment and technology to collect a large amount of data. Based on this, we strive to improve the quality of present products, develop new materials, and lead the way in the research and development of new fields; strengthening our basic technology and elemental technology capabilities. We work together with our customers in the design, analysis and verification of products, responding quickly and effectively to customers needs, and putting particular emphasis on providing a technological service that enables customers to use our products with peace of mind.

## 3D CAD Design Example

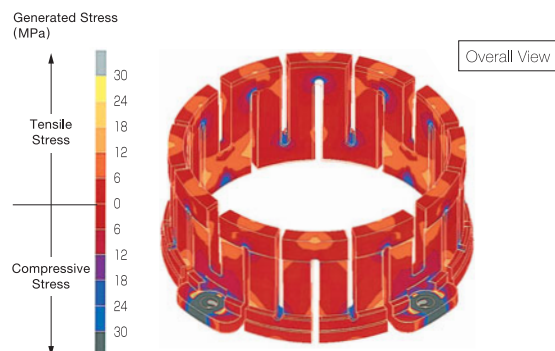


## Finite element method Analysis Example (FEM)

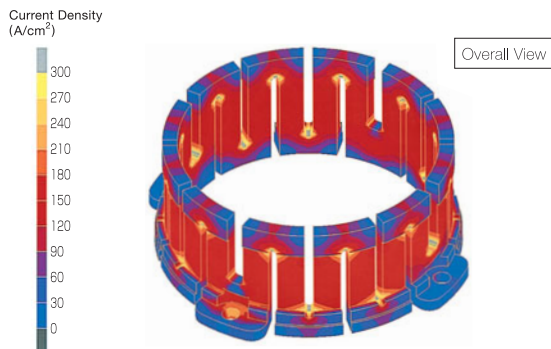
### Thermal Deformation Analysis Results



### Thermal Stress Analysis Results



### Current Density Distribution Results



Toyo Tanso uses the finite element method (FEM) to analyze factors such as product thermal deformation, thermal stress, and current density distribution, under conditions that are appropriate for our customers. We provide our customers with an integrated support system in the design process.

# Property Data

## ■ Typical Properties of Isotropic Graphite

Grade	Bulk Density	Hardness	Electrical Resistivity	Flexural Strength	Compressive Strength	Tensile Strength	Young's Modulus	Coefficient of Thermal Expansion	Thermal Conductivity	Standard Size	
	Mg/m <sup>3</sup>	HSD	$\mu\Omega\cdot m$	MPa	MPa	MPa	GPa	10 <sup>-6</sup> /K	W/(m·K)	(mm)	
IG-11	1.77	51	11.0	39	78	25	9.8	4.5	120	305×620×1000	D585×1050
IG-12	1.78	55	12.5	39	88	28	10.8	4.7	100	305×620×1000	D585×1050
IG-15	1.90	60	9.5	54	103	29	11.8	4.8	140	230×620×1000	
IG-19	1.75	60	17.0	38	88	25	9.5	4.6	80	D585×1050	
IG-43	1.82	55	9.2	54	90	37	10.8	4.8	140	300×540×850	
IG-45	1.88	55	9.0	60	110	40	12.0	4.9	140	300×540×850	
IG-56	1.77	57	12.2	43	88	27	10.3	4.7	100	1050×1050×450	D760×700
IG-70	1.83	58	10.0	47	103	31	11.8	4.6	130	305×620×1000	D460×1050
ISEM-1	1.68	45	13.5	36	69	20	8.8	4.2	90	305×620×1000	
ISEM-2	1.78	55	11.0	41	83	25	9.8	4.6	120	305×620×1000	
ISEM-3	1.85	60	10.0	49	103	29	11.8	5.0	130	305×620×1000	
ISEM-8	1.78	63	13.4	52	106	34	10.1	5.6	90	305×620×1000	
ISO-63	1.78	76	15.0	65	135	46	12.0	5.6	70	230×540×1000	
ISO-66	1.82	75	14.4	70	134	46	12.6	7.1	80	180×450×850	
ISO-68	1.82	80	15.5	76	172	54	13.2	5.6	70	230×540×1000	
SIC-6	1.85	60	10.0	49	103	29	11.8	5.0	130	305×620×1000	
SIC-12	1.77	65	14.1	47	93	29	10.8	5.0	80	305×620×1000	
TTK-4	1.78	72	14.0	73	135	49	10.9	5.0	90	210×510×950	
TTK-5	1.78	80	15.5	80	150	53	11.6	5.7	80	210×510×950	
TTK-50	1.80	70	13.0	60	130	40	11.5	5.1	100	305×620×1000	

※The figures above are typical values, and are not guaranteed.

※The measurement temperature range for the coefficient of thermal expansion is 350 to 450°C.

※Unit conversion:  $\mu\Omega\cdot m = \mu\Omega\cdot cm \times 0.01$  MPa=kgf/cm<sup>2</sup>×0.098 GPa=kgf/mm<sup>2</sup>×0.0098 W/(m·K)=kcal/h·m·°C×1.16

※There are other product sizes in addition to those described above. Contact Toyo Tanso for details.

※Size or specification of material may be changed without notice.

※Standard size is nominal dimension.

## ■ Impurity Analysis Example

Unit: mass ppm

Element	Content			Measurement Method
	Ultra High Purity Graphite	High Purity Graphite	Regular Graphite	
Li	<0.001	<0.001	<0.03	ICP-MS
B	0.10	0.15	3	ICP-MS
Na	<0.002	<0.002	<0.5	ICP-MS
Mg	<0.001	0.004	0.2	ICP-MS
Al	<0.001	0.012	14	ICP-MS
Si	<0.1	<0.1	2	UV
K	<0.03	0.04	2	FL-AAS
Ca	<0.01	0.08	6	FL-AAS
Ti	<0.001	<0.001	33	ICP-MS

Element	Content			Measurement Method
	Ultra High Purity Graphite	High Purity Graphite	Regular Graphite	
V	<0.001	0.018	40	ICP-MS
Cr	<0.004	0.006	<0.3	ICP-MS
Mn	<0.001	<0.001	<0.2	ICP-MS
Fe	<0.02	0.06	26	ICP-MS
Co	<0.001	<0.001	<0.3	ICP-MS
Ni	<0.001	0.006	4	ICP-MS
Cu	<0.002	<0.002	<1	ICP-MS
Zn	<0.002	<0.002	<0.6	ICP-MS
Pb	<0.001	<0.001	<1	ICP-MS

※The figures above are examples of actual measurements, and are not guaranteed.

※ICP-MS: Inductively Coupled Plasma Mass Spectrometer, FL-AAS: Flameless Atomic Absorption Spectrometer, UV: Absorption Spectrophotometer.

※The impurity content of regular graphite is approximately 400 mass ppm; however, a higher purity is required for applications such as semi-conducting industries. At Toyo Tanso, we can use a high temperature halogen treatment to purify the graphite to the mass ppm levels requested by our customers.

## Chemical Properties

### Initial Reaction Temperatures With Various Substances

※Extracted from other publications

Reactant	Initial Reaction Temperature	Compound of Reaction
Aluminum	800℃	Al <sub>4</sub> C <sub>3</sub>
Boron	1600℃	B <sub>4</sub> C
Iron	600~800℃	Fe <sub>3</sub> C
Sodium	400~450℃	C <sub>64</sub> Na <small>Intercalation compound (when O<sup>2-</sup> is present)</small>
Cobalt	218℃	CoC, Co <sub>3</sub> C
Molybdenum	700℃	Mo <sub>2</sub> C
Nickel	1310℃	Ni <small>Carbonizing in Ni</small>
Silicon	1150℃	SiC
Copper	————	
Magnesium	————	
Lead	————	
Tin	————	
Tungsten	1400℃	W <sub>2</sub> C, WC (in hydrogen)
Potassium	300℃	C <sub>8</sub> K <small>Other intercalation compounds</small>
Lithium	500℃	Li <sub>2</sub> C <sub>2</sub>
Beryllium	900℃	Be <sub>2</sub> C (in a vacuum or He)
Boron oxide	1200℃	CO, B
Vanadium oxide (V)	438℃	CO, V
Iron oxide (III)	485℃	CO, Fe
Titanium oxide (IV)	930℃	CO, Ti, TiC
Silicon dioxide	1250℃	CO, Si, SiC
Alumina	1280℃	CO, Al, Al <sub>4</sub> C <sub>3</sub>
Beryllium oxide	960℃	CO, Be, Be <sub>2</sub> C
Magnesium oxide	1350℃	CO, Mg
Zirconium oxide (IV)	1300℃	CO, Zr, ZrC

### Initial Reaction Temperatures in Gas

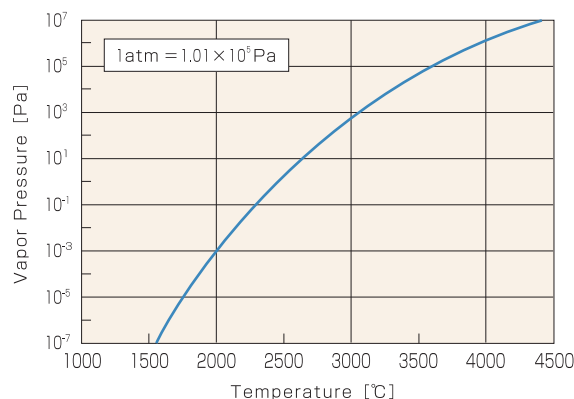
※Extracted from other publications

Atmospheric Gas	Initial Reaction Temperature	Reaction
Air	380~400℃	Oxidization
Water vapor	700~750℃	Oxidization
Carbon dioxide	800~900℃	Oxidization
Hydrogen	1000~1200℃	Methanation
Nitrogen	2000~2500℃	Cyaniding
Chlorine	2500℃	Graphite sublimation
Argon	3000℃	Graphite sublimation
Vacuum	2200℃	Graphite sublimation

In an oxidizing atmosphere, graphite reacts with oxygen at a relatively low temperature. However, in a non-oxidizing atmosphere, graphite is chemically and thermally an extremely stable material, enabling a broad range of applications.

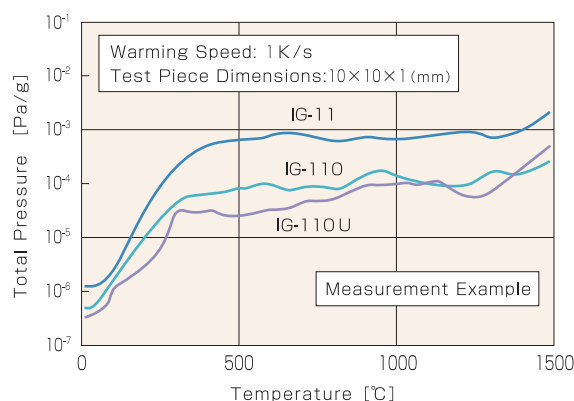
### Vapor Pressure

※Extracted from other publications



Graphite is an extremely stable material in temperatures under 2,200℃. However, the vapor pressure increases in higher temperatures and high vacuums, so caution must be exercised with regard to the accelerated wearing of graphite.

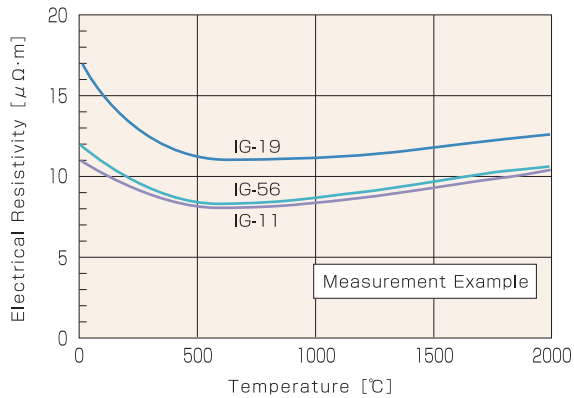
### Thermal Desorption Spectrum (TDS)



Graphite emits absorbed gas when in high temperatures. Some applications such as semi-conducting industries must use high purified or ultra high purified graphite, which emits less gas.

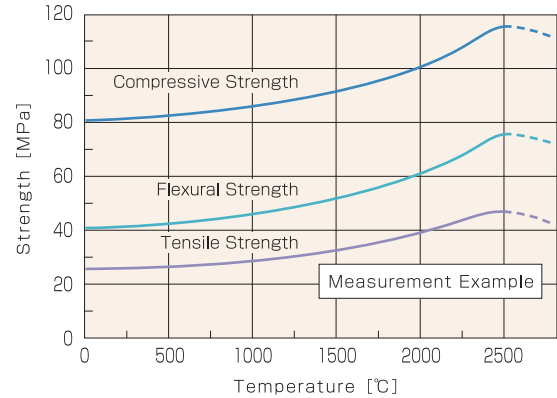
■ High Temperature Properties

■ Electrical Resistivity



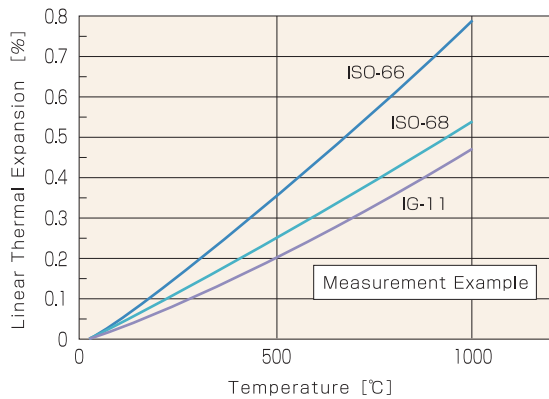
Since thermal characteristics differ from grade to grade, the coefficient of electrical resistivity must be carefully studied when selecting a grade for a heating element.

■ Strengths (IG-11)

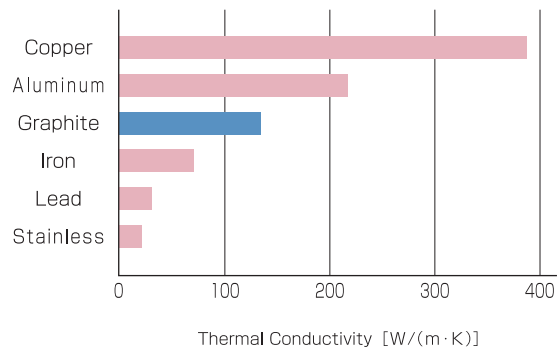
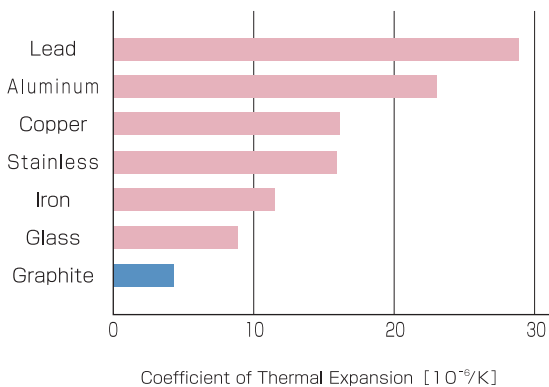
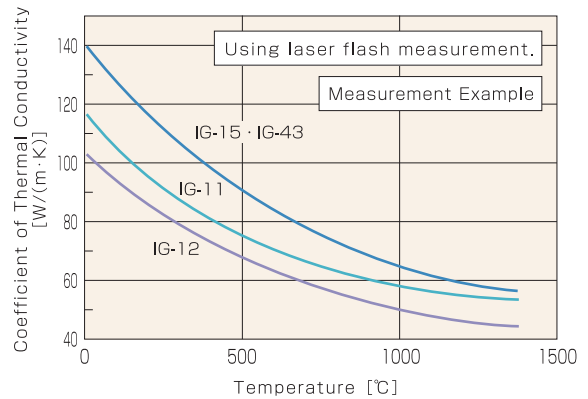


An unparalleled characteristic of graphite, which makes it indispensable in high temperature applications, is that as the temperature rises (up to 2,500C), the strength also increases. Strength reaches levels approximately double those at room temperature.

■ Linear Thermal Expansion



■ Thermal Conductivity



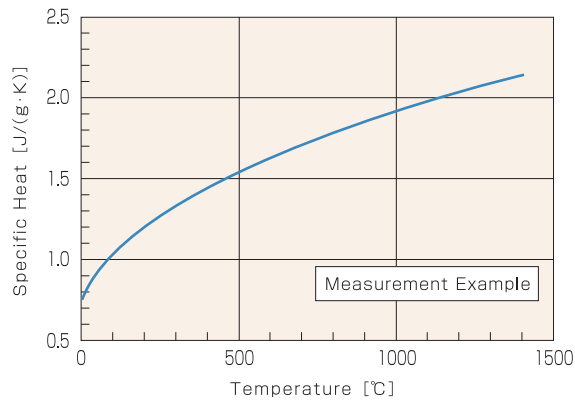
Compared with general metals, the coefficient of thermal expansion for graphite is extremely low. As a result, when used in high temperature applications, the dimensional accuracy is very stable.

The thermal conductivity of graphite is fairly high, while the coefficient of thermal expansion is very low. These characteristics contribute to its superior thermal shock resistance. The relationship between thermal conductivity and electrical resistivity of graphite in room temperature is indicated below.

$$\text{Reference: Coefficient of Thermal Expansion} = \frac{\text{Linear Thermal Expansion (\%)} \times 10^{-2}}{\text{Temperature Difference (}^\circ\text{C)}}$$

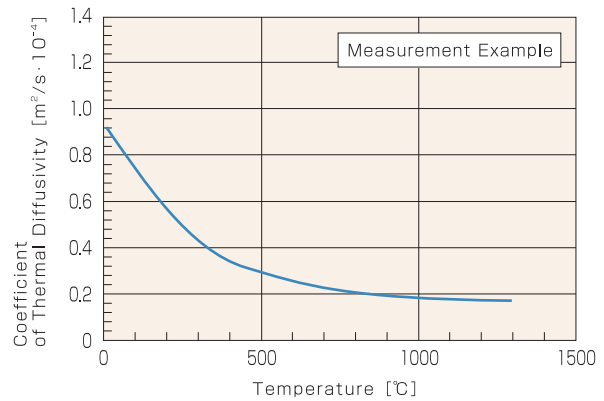
$$\text{Thermal Conductivity [W/(m·K)]} = \frac{0.13 \times 10^4}{\text{Electrical Resistivity (\mu}\Omega \cdot \text{m)}}$$

■ Specific Heat



Due to the anisotropic nature of its crystals, the specific heat of graphite at room temperature stays at 1/3 of that of general solids. The specific heat value is essential in various thermodynamic functions. At high temperatures, specific heat values are similar regardless of the graphite grades.

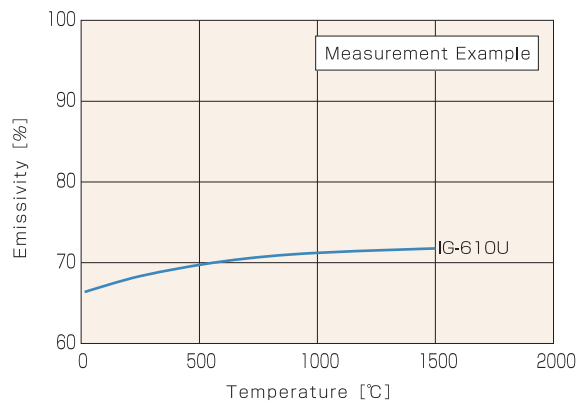
■ Coefficient of Thermal Diffusivity



This chart shows that the higher the temperature rises, the faster the heat is transmitted. The thermal diffusivity of graphite is superior to other materials.

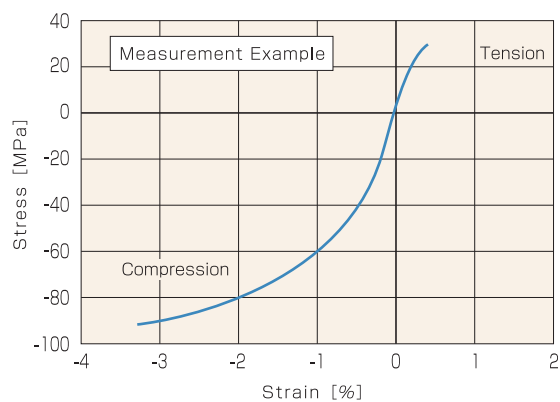
Reference:  
 Coefficient of Thermal Diffusivity =  $\frac{\text{Thermal Conductivity}}{\text{Specific Heat} \times \text{Density}}$

■ Emissivity



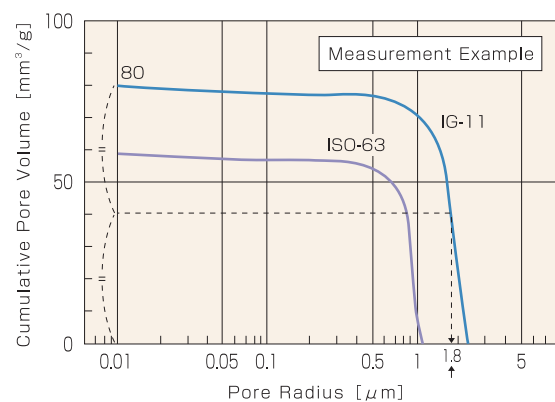
■ Physical Properties

■ Stress Strain Curve (IG-12)



Graphite generally shows elastic-plastic deformation. The fracture behavior is different under tension and under compression, so caution must be exercised.

■ Pore Distribution Curve



This shows the pore distribution through the mercury penetration method. The pore distribution has a close relationship with gas permeability and other unique properties of graphite. The halfway position of the cumulative pore volume indicates the average pore radius.

Example: For IG-11  $80/2=40\text{mm}^3/\text{g} \rightarrow 1.8\mu\text{m}$

# Machining

## ■ Surface Roughness Standards

Since carbon products are porous, it is difficult to obtain a surface finish that is equivalent to metal. The table on the right shows the correspondence of the "Surface Finish Symbol" and surface roughness standards, Ry & Ra & Rz.

## ■ Surface Roughness Standards

Finish Symbol (For reference)	Machining Surface Roughness for Carbon			Finishing Method	Machining Surface Roughness for Metal		
	Ry	Ra	Rz		Ry	Ra	Rz
▽▽▽▽	√Ry3	0.75/√	√Rz3	Honing Lapping	√Ry0.8	0.2/√	√Rz0.8
▽▽▽	√Ry12	3.0/√	√Rz12	Grinder, Lathe Miller	√Ry6.3	1.6/√	√Rz6.3
▽▽	√Ry35	8.75/√	√Rz35	Lathe Miller	√Ry25	6.3/√	√Rz25
▽	√Ry100	25/√	√Rz100	Lathe Miller	√Ry100	25/√	√Rz100
~	No particular standard			Saw Machine	No particular standard		

\* 3.0/√ means that Ra 3.0 micro meter is the maximum.

## ■ Machining Dimension Tolerance

If the tolerance is not specified on the customer drawing, apply the intermediate grade of JIS B 0405.

## ■ Dimension Tolerance Standards

Unit:mm

Nominal Dimension Category		Tolerance
0.5 or more	6 or less	±0.1
Exceeding 6	30 or less	±0.2
Exceeding 30	120 or less	±0.3
Exceeding 120	400 or less	±0.5
Exceeding 400	1000 or less	±0.8
Exceeding 1000	2000 or less	±1.2

\*The above information can be applied when graphite is machined by Toyo Tanso in Japan.

Toyo Tanso has a wide range of graphite grades available to meet every kind of need. Before actually using one of our products, please be sure to contact our sales department to consult on selecting the most appropriate grade.

# PERMA KOTE Products

PERMA KOTE is a product created by coating the surface of highly purified isotropic graphite with a fine layer of silicon carbide by means of a proprietary Toyo Tanso Chemical Vapor Deposition (CVD) process.

## ■PERMA KOTE Characteristics

- The silicon carbide layer has excellent oxidation resistance, corrosion resistance and chemical resistance.
- The silicon carbide layer is stable at high temperatures and is extremely hard.
- Prevents the parting and scattering of graphite particles, and the emission of gas and impurities from the graphite substrate.
- Both the graphite substrate and silicon carbide layer are of high purity.
- Both the graphite substrate and silicon carbide layer have a high thermal conductivity, and excellent heat distribution properties.
- Material is designed so that cracks and delamination do not occur.

## ■Coating Thickness

The standard thickness is 120  $\mu\text{m}$ ; however this can be modified within a range of 20 to 500  $\mu\text{m}$ .

## ■Application

- Susceptors for silicon epitaxial growth
- Single crystal silicon manufacturing equipment
- MOCVD susceptors
- Heaters
- Heat spreaders
- Oxidation resistance components



Silicon Epitaxial Growth System

■ PERMA KOTE Property Data

■ Corrosion Resistance

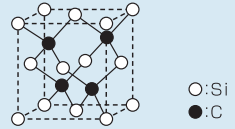
Name	Chemical Formula	Concentration (%)	Temperature (°C)	Time (h)	Change in Mass (g/m <sup>2</sup> )
Hydrofluoric acid	HF	47	80	144	-1.0
Hydrochloric acid	HCl	36	Boiling point	144	0
Sulfuric acid	H <sub>2</sub> SO <sub>4</sub>	97	110	144	0
Nitric acid	HNO <sub>3</sub>	61	Boiling point	144	0
Hydrofluoric acid+nitric acid	HF+HNO <sub>3</sub> (1:1)	100	80	288	-1.0
Nitric acid + sulfuric acid	HNO <sub>3</sub> +H <sub>2</sub> SO <sub>4</sub> (1:1)	100	25	288	-1.0
Sodium hydroxide	NaOH	20	80	288	0
Phosphoric acid	H <sub>3</sub> PO <sub>4</sub>	100	100	192	-1.0
Nitrohydrochloric acid	HCl+HNO <sub>3</sub> (3:1)	100	80	192	0

■ Reactivity With Various Substances (In a Vacuum)

Reactant	Chemical Formula	1200°C×3h	1600°C×3h
Aluminum	Al	○	△
Boron	B	◎	◎
Cobalt	Co	△	×
Chromium	Cr	△	×
Copper	Cu	○	△
Iron	Fe	×	×
Molybdenum	Mo	◎	○
Nickel	Ni	◎	×
Lead	Pb	△	×
Silicon	Si	◎	○
Tin	Sn	◎	△
Tantalum	Ta	◎	◎
Titanium	Ti	◎	○
Vanadium	V	◎	×
Tungsten	W	◎	○
Alumina	Al <sub>2</sub> O <sub>3</sub>	◎	×
Boron oxide	B <sub>2</sub> O <sub>3</sub>	◎	◎
Chromium oxide (III)	Cr <sub>2</sub> O <sub>3</sub>	◎	×
Iron oxide (III)	Fe <sub>2</sub> O <sub>3</sub>	×	×
Magnesium oxide	MgO	◎	△
Manganese oxide (IV)	MnO <sub>2</sub>	◎	×
Lead oxide (II)	PbO	○	△
Silicon dioxide	SiO <sub>2</sub>	◎	△
Titanium oxide (IV)	TiO <sub>2</sub>	◎	○
Vanadium oxide (V)	V <sub>2</sub> O <sub>5</sub>	◎	△
Zirconium oxide (IV)	ZrO <sub>2</sub>	◎	○

※◎...No reaction ○...Slight reaction  
 △...Reaction ×...Significant reaction

■ Layer Properties

Crystal Structure	β-SiC(Cubic System) Structure	
		
Bulk Density	3.2Mg/m <sup>3</sup>	
Hardness	2800HK	
Electrical Resistivity	0.2Ω·m (through the fall-of-potential method)	
Flexural Strength	170MPa (through 3-point bending)	
Young's Modulus	320GPa (through the deflection method)	

※The figures above are extracted from other publications or are measurement examples, and are not guaranteed.

■ Impurity Analysis Example

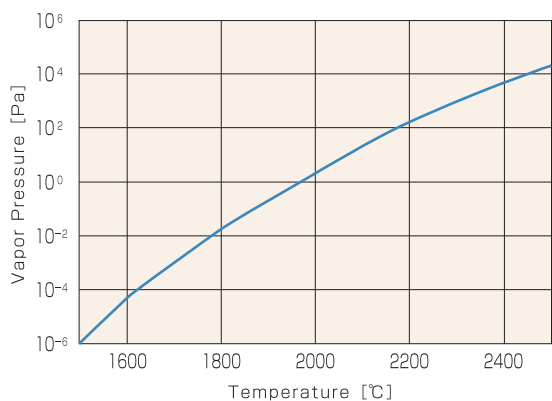
Unit:mass ppm

Element	Content
B	0.15
Na	0.02
Al	0.01
Cr	<0.1
Fe	0.02
Ni	<0.01

※Measurement method:Glow Discharge Mass Spectrometry  
 ※The figures above are measurement examples and are not to be guaranteed.

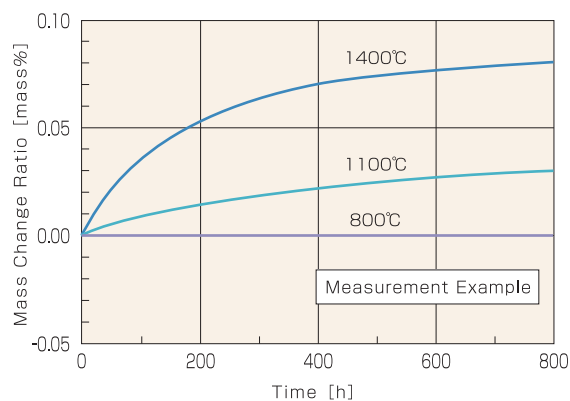
■ Silicon Carbide Vapor Pressure

※Extracted from the ultra high temperature melting point material handbook



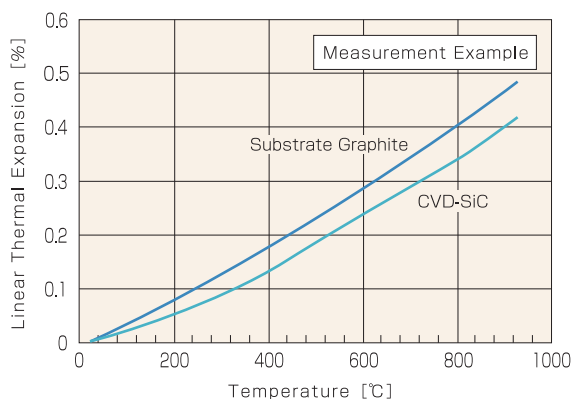
PERMA KOTE is extremely stable at high temperatures.

■ Oxidization

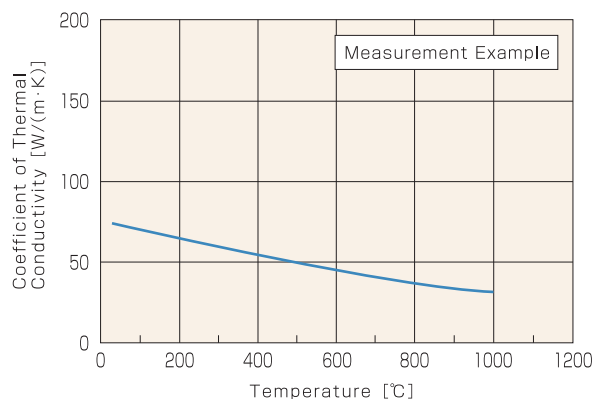


PERMA KOTE is resistant to oxidation; and because the SiO<sub>2</sub> protective layer is formed at over 800°C, the substrate graphite is protected from oxidation.

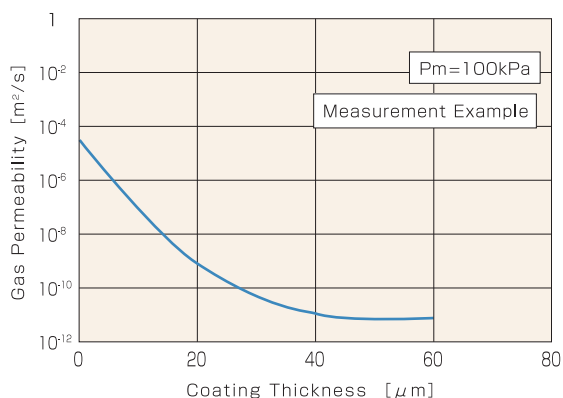
■ Coefficient of Thermal Expansion for CVD-SiC and Substrate graphite



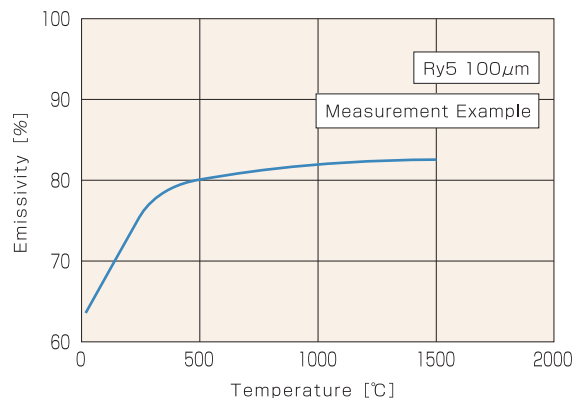
■ Thermal Conductivity



■ Gas Permeability



■ Emissivity



# PYROGRAPH Products

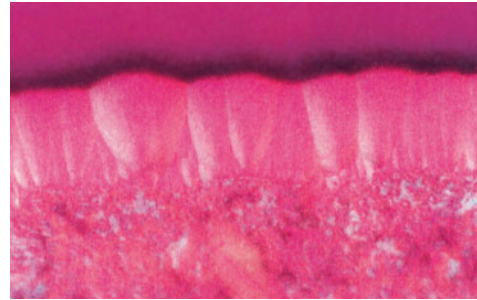
PYROGRAPH is a product created by coating the surface of highly purified isotropic graphite with a fine layer of pyrolytic carbon by means of a proprietary Toyo Tanso Chemical Vapor Deposition (CVD) process.

## ■ PYROGRAPH Characteristics

- the pyrolytic carbon layer is extremely fine
- ultrapure
- the layer coating ensures extremely low gas permeability
- excellent corrosion resistance against gas
- excellent oxidation resistance at low temperatures
- excellent heat resistance
- prevents the parting and scattering of graphite particles, and the emission of gas and impurities from the graphite substrate

PYROGRAPH Cross Section

20μm



The column-shaped structure of the pyrolytic carbon layer means that the structure is extremely fine.

## ■ Application

- Single crystal silicon manufacturing equipment
- Tube for atomic absorption spectroscopy
- OLED manufacturing equipment

## ■ PYROGRAPH Property Data

### ■ Impurity Analysis Example

Unit: mass ppm

Element	Content
B	<0.01
Na	0.03
Al	0.02
Cr	<0.10
Fe	<0.01
Ni	<0.01

※ \*Measurement method: Glow Discharge Mass Spectrometry  
 ※ The figures above are measurement examples, and are not to be guaranteed.

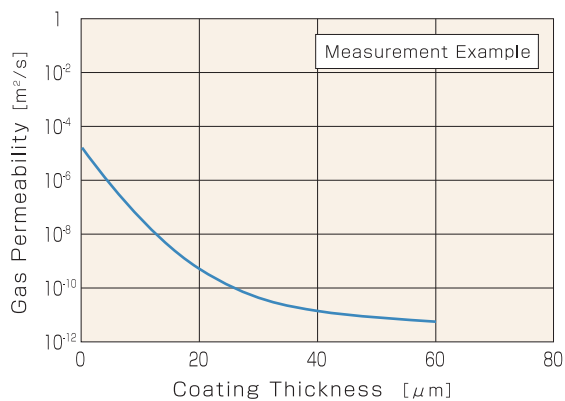
### ■ General Physical Properties

Item	Unit	Parallel to Coating Surface	Perpendicular to Coating Surface
Bulk Density	Mg/m <sup>3</sup>	2.2	2.2
Hardness	HSD	100	—
Electrical Resistivity	μΩ·m	2.00~4.00	2~5×10 <sup>3</sup>
Coefficient of Thermal Expansion	10 <sup>-6</sup> /K	1.7	28
Tensile Strength	MPa	98~147	Extremely weak
Young's Modulus	GPa	29~39	—
Thermal Conductivity	W/(m·K)	170~420	2~4

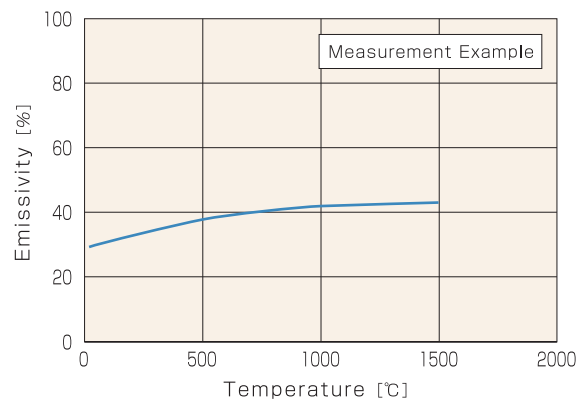
※ The temperature range for the coefficient of thermal expansion is RT to 1,000°C.

※ The figures above are extracted from other publications, and are not to be guaranteed.

### ■ Gas Permeability



### ■ Emissivity



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